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Docket No.: 005199 USA/Consilium/Consilium

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6-2-03



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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re Application of

Yueshian T. CHI et al.

Serial No. 09/725,908

: Group Art Unit: 2152

Filed: November 30, 2000

: Examiner:

For: DYNAMIC SUBJECT INFORMATION GENERATION IN MESSAGE SERVICES OF
DISTRIBUTED OBJECT SYSTEMS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

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to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "Scott M. Alter". The signature is fluid and cursive, with the first name "Scott" being more prominent.

Scott M. Alter

Registration No. 32,879

1455 Pennsylvania Avenue, NW
Washington, DC 20004
TEL 202.942.8428 SMA/lrm
FAX 202.942.8484
Date: 4/25/03

INFORMATION DISCLOSURE
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ATTY. DOCKET NO.
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						Yes	No
	61-66104	04/04/86	Japan			X	
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	0 869 652	10/07/98	Europe			X	
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	WO 00/00874	01/06/00	WIPO			X	
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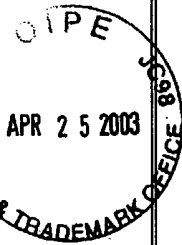
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	1 071 128	01/24/01	Europe			X	
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	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
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